MITSUI
KINZOKU

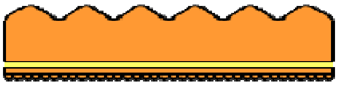
MT18FL

- MicroThin為附18μm載體銅箔的超薄銅箔。
  MicroThin is ultra thin foil with 18μm carrier foil.
- 適用於線寬/線距(L/ S) = 20/20或以下之應用。
  Usable for fine pitch pattern L/S = 20/20 or less formation.
- 與MT18Ex相比較，其更低的粗糙度更適用於極細線路之應用。
  Lower profile compare with MT18Ex, more suitable for very fine pattern.

用途/Application

・IC封裝載板
/Semiconductor Package

構成/Composition



生產地點/Production Site

・日本 / Japan

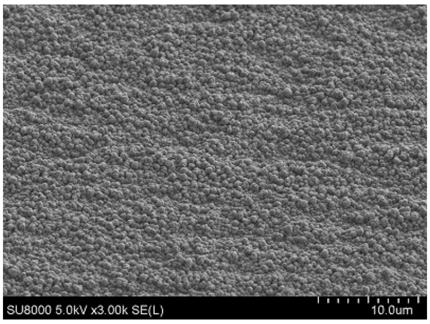
代表性特性數據/Representive

	μm	Area weight (g/m2)	Laminate side Rz(μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)@FR-4
MT18FL	1.5	18	1.3	－	－	1.2
	2	21	1.3	－	－	1.2
	3	30	1.3	－	－	1.2

※上述表列為代表性數據非保証值
This is representative data, not guaranteed.

※Peel Strength為增鍍到35μm厚度之後的測試值
Evaluated after plated up to 35μm。

處理面/Laminate side



阻劑面/ resist side